# TLV5616C, TLV5616I 2.7 V TO 5.5 V LOW POWER 12-BIT DIGITAL-TO-ANALOG CONVERTERS WITH POWER DOWN

SLAS152A - DECEMBER 1997 - REVISED SEPTEMBER 1998

- 12-Bit Voltage Output DAC
- Programmable Settling Time vs Power Consumption

3  $\mu$ s in Fast Mode 9  $\mu$ s in Slow Mode

- Ultra Low Power Consumption:
   900 μW Typ in Slow Mode at 3 V
   2.1 mW Typ in Fast Mode at 3 V
- Differential Nonlinearity . . . < 0.5 LSB Typ
- Compatible With TMS320 and SPI Serial Ports
- Power-Down Mode (10 nA)

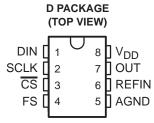
# description

The TLV5616 is a 12-bit voltage output digital-to-analog converter (DAC) with a flexible 4-wire serial interface. The 4-wire serial interface allows glueless interface to TMS320, SPI, QSPI, and Microwire serial ports. The TLV5616 is programmed with a 16-bit serial string containing 4 control and 12 data bits. Developed for a wide range of supply voltages, the TLV5616 can operate from 2.7 V to 5.5 V.

- Buffered High-Impedance Reference Input
- Voltage Output Range ... 2 Times the Reference Input Voltage
- Monotonic Over Temperature

# applications

- Digital Servo Control Loops
- Digital Offset and Gain Adjustment
- Industrial Process Control
- Machine and Motion Control Devices
- Mass Storage Devices



The resistor string output voltage is buffered by a x2 gain rail-to-rail output buffer. The buffer features a Class AB output stage to improve stability and reduce settling time. The settling time of the DAC is programmable to allow the designer to optimize speed versus power dissipation. The settling time is chosen by the control bits within the 16-bit serial input string. A high-impedance buffer is integrated on the REFIN terminal to reduce the need for a low source impedance drive to the terminal.

Implemented with a CMOS process, the TLV5616 is designed for single supply operation from 2.7 V to 5.5 V. The device is available in an 8-terminal SOIC package. The TLV5616C is characterized for operation from  $0^{\circ}$ C to  $70^{\circ}$ C. The TLV5616I is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

#### **AVAILABLE OPTIONS**

	PACKAGE
TA	SMALL OUTLINE† (D)
0°C to 70°C	TLV5616CD
-40°C to 85°C	TLV5616ID

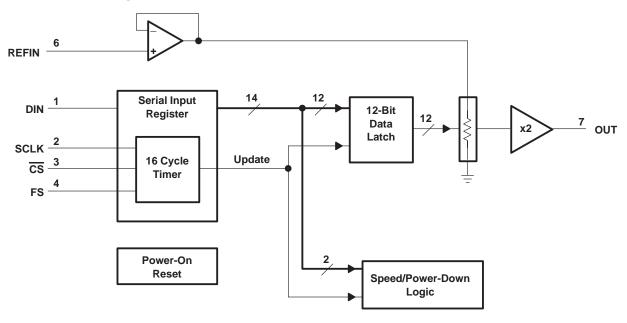
† Available in tape and reel as the TLV5616CDR and the TLV5616IDR



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



# functional block diagram



# **Terminal Functions**

TERMI	TERMINAL I/O		DESCRIPTION
NAME	NO.	1/0	DESCRIPTION
AGND	5		Analog ground
CS	3	Ι	Chip select. Digital input used to enable and disable inputs, active low.
DIN	1	Ι	Serial digital data input
FS	4	I	Frame sync. Digital input used for 4-wire serial interfaces such as the TMS320 DSP interface.
OUT	7	0	DAC analog output
REFIN	6	Ι	Reference analog input voltage
SCLK	2	Ī	Serial digital clock input
$V_{DD}$	8		Positive power supply



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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

S	upply voltage (V <sub>DD</sub> to AGND)	
	eference input voltage range	
	igital input voltage range	
	perating free-air temperature range, TA: TLV5616C	
	TLV5616I	40°C to 85°C
S	torage temperature range, T <sub>stq</sub>	65°C to 150°C
L	ead temperature 1.6 mm (1/16 inch) from case for 10 seconds	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, VDD	V <sub>DD</sub> = 5 V	4.5	5	5.5	V
Supply voltage, vDD	V <sub>DD</sub> = 3 V	2.7	3	3.3	V
High-level digital input voltage, VIH	V <sub>DD</sub> = 2.7 V to 5.5 V	2			V
Low-level digital input voltage, V <sub>IL</sub>	V <sub>DD</sub> = 2.7 V to 5.5 V			0.8	V
Reference voltage, V <sub>ref</sub> to REFIN terminal	V <sub>DD</sub> = 5 V (see Note 1)	AGND	2.048	V <sub>DD</sub> -1.5	V
Reference voltage, V <sub>ref</sub> to REFIN terminal	V <sub>DD</sub> = 3 V (see Note 1)	AGND	1.024	V <sub>DD</sub> -1.5	V
Load resistance, R <sub>L</sub>		2	10		kΩ
Load capacitance, CL				100	pF
Clock frequency, f <sub>CLK</sub>				20	MHz
Operating free-air temperature, Тд	TLV5616C	0		70	°C
Operating nee-all temperature, 14	TLV5616I	-40		85	°C

NOTE 1: Due to the x2 output buffer, a reference input voltage  $\geq V_{DD/2}$  causes clipping of the transfer function.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

#### power supply

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
			V <sub>DD</sub> = 5 V, VREF = 2.048 V, No load,	Fast		0.9	1.35	mA
	Power supply current	All inputs = AGND or V <sub>DD</sub> , DAC latch = 0x800	Slow		0.4	0.6	mA	
IDD	Fower supply current		V <sub>DD</sub> = 3 V, VREF = 1.024 V No load,	Fast		0.7	1.1	mA
		All inputs = AGND or V <sub>DD</sub> , DAC latch = 0x800	Slow		0.3	0.45	mA	
	Power down supply current (see Figure	12)			10		nA	
PSRR	Power supply rejection ratio  Zero scale  Full scale		See Note 2		-80		dB	
FORK			See Note 3		-80		uБ	
	Power on threshold voltage, POR		·		2		V	

NOTES: 2. Power supply rejection ratio at zero scale is measured by varying  $V_{DD}$  and is given by:  $PSRR = 20 log [(E_{ZS}(V_{DD}max) - E_{ZS}(V_{DD}min))/V_{DD}max]$ 

 Power supply rejection ratio at full scale is measured by varying V<sub>DD</sub> and is given by: PSRR = 20 log [(Eg(V<sub>DD</sub>max) – Eg(V<sub>DD</sub>min))/V<sub>DD</sub>max]



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

# static DAC specifications $R_L = 10 \text{ k}\Omega$ , $C_L = 100 \text{ pF}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Resolution			12	12	bits
INL	Integral nonlinearity	See Note 4		± 1.9	±4	LSB
DNL	Differential nonlinearity	See Note 5		± 0.5	± 1	LSB
EZS	Zero-scale error (offset error at zero scale)	See Note 6			±10	mV
	Zero-scale-error temperature coefficient	See Note 7		10		ppm/°C
E <sub>G</sub>	Gain error	See Note 8			±0.6	% of FS voltage
	Gain-error temperature coefficient	See Note 9		10		ppm/°C

- NOTES: 4. The relative accuracy or integral nonlinearity (INL) sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale excluding the effects of zero code and full-scale errors.
  - 5. The differential nonlinearity (DNL) sometimes referred to as differential error, is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.
  - 6. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
  - 7. Zero-scale-error temperature coefficient is given by: EZS TC = [EZS (T<sub>max</sub>) EZS (T<sub>min</sub>)]/V<sub>ref</sub> × 10<sup>6</sup>/(T<sub>max</sub> T<sub>min</sub>).
  - 8. Gain error is the deviation from the ideal output ( $2V_{ref} 1$  LSB) with an output load of 10 k $\Omega$  excluding the effects of the zero-error. 9. Gain temperature coefficient is given by:  $E_G TC = [E_G(T_{max}) E_G(T_{min})]/V_{ref} \times 10^6/(T_{max} T_{min})$ .

# output specifications

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VO	Voltage output range	$R_L = 10 \text{ k}\Omega$	0		AV <sub>DD</sub> -0.1	V
	Output load regulation accuracy	$R_L$ = 2 kΩ, vs 10 kΩ		0.1	±0.25	% of FS voltage

#### reference input (REF)

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
VI	Input voltage range	1201 00110110110		0		V <sub>DD</sub> -1.5	V
R <sub>I</sub>	Input resistance				10		ΜΩ
Cl	Input capacitance				5		pF
	Potoronoo input hondwidth	PEEIN - 0.3 V + 1.034 V do	Slow		525		kHz
	Reference input bandwidth	REFIN = 0.2 V <sub>pp</sub> + 1.024 V dc			1.3		MHz
	Reference feed through	REFIN = 1 V <sub>pp</sub> at 1 kHz + 1.024 V dc (see Note 10)		-75	·	dB	

NOTE 10: Reference feedthrough is measured at the DAC output with an input code = 0x000.

#### digital inputs

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
lн	High-level digital input current	$V_I = V_{DD}$			±1	μΑ
Iլլ	Low-level digital input current	V <sub>I</sub> = 0 V			±1	μΑ
CI	Input capacitance			3	·	pF



# operating characteristics over recommended operating free-air temperature range (unless otherwise noted)

# analog output dynamic performance

	PARAMETER	TES	ST CONDITIONS		MIN	TYP	MAX	UNIT
t (=0)	Output pottling time, full people	$R_L = 10 \text{ k}\Omega$ ,	C <sub>L</sub> = 100 pF,	Fast		3	5.5	
ts(FS)	Output settling time, full scale	See Note 11		Slow		9	20	μs
	Output settling time, code to code	$R_L = 10 \text{ k}\Omega$ ,	C <sub>L</sub> = 100 pF,	Fast		1		μs
ts(CC)	Output setting time, code to code	See Note 12		Slow		2		μs
SR	Slew rate	$R_L = 10 \text{ k}\Omega$ ,	C <sub>L</sub> = 100 pF,	Fast		3.6		V/μs
J SK		See Note 13		Slow		0.9	.9 V/μs	
	Glitch energy	Code transition	from 0x7FF to 0x800	)		10		nV-s
S/N	Signal to noise					74		dB
S/(N+D)	Signal to noise + distortion	fs = 400 KSPS fout = 1.1 kHz,				66		dB
THD	Total harmonic distortion	$R_L = 10 \text{ k}\Omega$ , BW = 20 kHz	$C_L = 100 \text{ pF},$			-68		dB
	Spurious free dynamic range	]				70		dB

- NOTES: 11. Settling time is the time for the output signal to remain within ±0.5 LSB of the final measured value for a digital input code change of 0x080 to 0x3FF or 0x3FF to 0x080. Not tested, ensured by design.
  - 12. Settling time is the time for the output signal to remain within  $\pm$  0.5 LSB of the final measured value for a digital input code change of one count. Code change from 0x1FF to 0x200. Not tested, ensured by design.
  - 13. Slew rate determines the time it takes for a change of the DAC output from 10% to 90% full-scale voltage.

# digital input timing requirements

		MIN	NOM	MAX	UNIT
t <sub>su(CS-FS)</sub>	Setup time, CS low before FS↓	10			ns
t <sub>su(FS-CK)</sub>	Setup time, FS low before first negative SCLK edge	8			ns
tsu(C16–FS)	Setup time, sixteenth negative edge after FS low on which bit D0 is sampled before rising edge of FS	10			ns
tsu(C16–CS)	Setup time, sixteenth positive SCLK edge (first positive after D0 is sampled) before $\overline{\text{CS}}$ rising edge. If FS is used instead of the sixteenth positive edge to update the DAC, then the setup time is between the FS rising edge and $\overline{\text{CS}}$ rising edge.	10			ns
t <sub>wH</sub>	Pulse duration, SCLK high	25			ns
t <sub>W</sub> L	Pulse duration, SCLK low	25			ns
t <sub>su(D)</sub>	Setup time, data ready before SCLK falling edge	8			ns
t <sub>h(D)</sub>	Hold time, data held valid after SCLK falling edge	5			ns
<sup>t</sup> wH(FS)	Pulse duration, FS high	20			ns

# PARAMETER MEASUREMENT INFORMATION

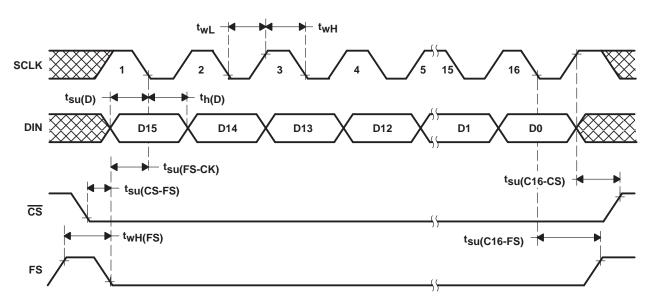
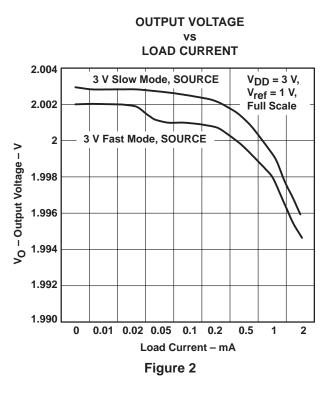
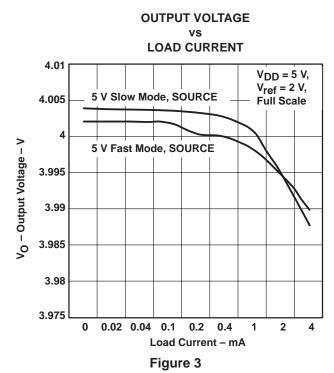


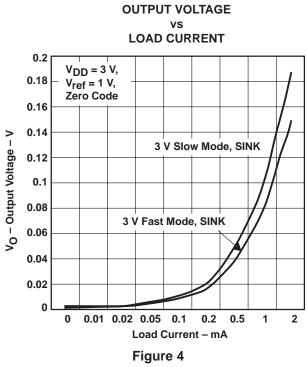
Figure 1. Timing Diagram

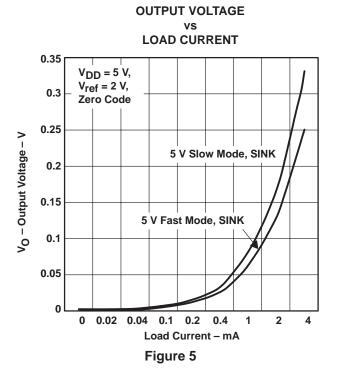


#### **TYPICAL CHARACTERISTICS**

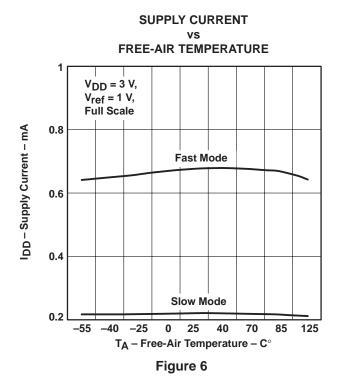


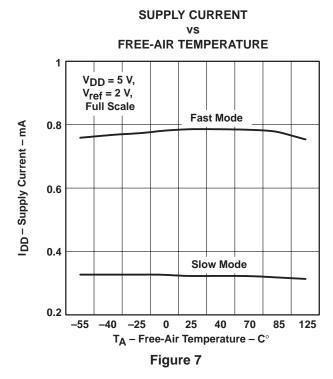




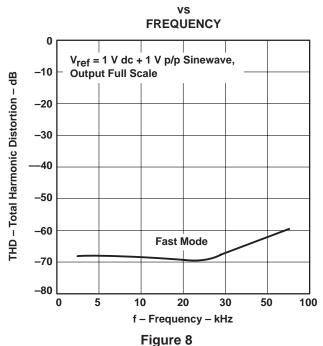


#### TYPICAL CHARACTERISTICS

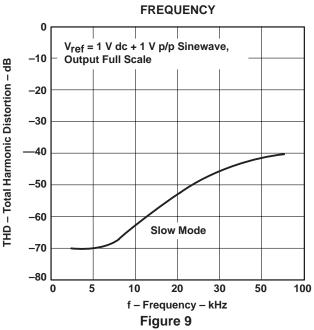




TOTAL HARMONIC DISTORTION







#### TYPICAL CHARACTERISTICS

# TOTAL HARMONIC DISTORTION AND NOISE **FREQUENCY** V<sub>ref</sub> = 1 V dc + 1 V p/p Sinewave, Output Full Scale

THD - Total Harmonic Distortion And Noise - dB -10-20 -30 --40 -50 **Fast Mode** -60

Figure 10

20

f - Frequency - kHz

30

50

10

-70

-80

0

5

# TOTAL HARMONIC DISTORTION AND NOISE

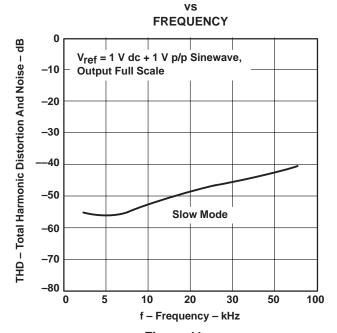


Figure 11

#### SUPPLY CURRENT

100

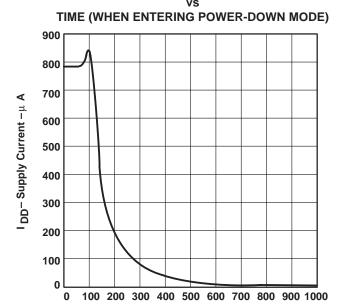


Figure 12

T - Time - ns

#### TYPICAL CHARACTERISTICS

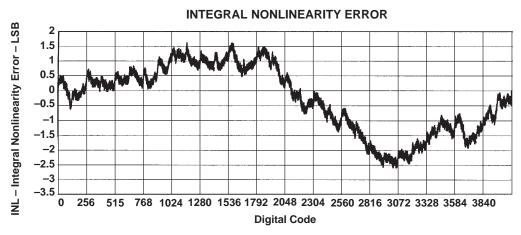


Figure 13

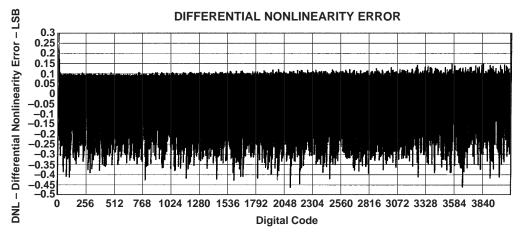


Figure 14



#### APPLICATION INFORMATION

# general function

The TLV5616 is a 12-bit single supply DAC based on a resistor string architecture. The device consists of a serial interface, speed and power-down control logic, a reference input buffer, a resistor string, and a rail-to-rail output buffer.

The output voltage (full scale determined by external reference) is given by:

2 REF 
$$\frac{\text{CODE}}{0 \times 1000}$$
 [V]

Where REF is the reference voltage and CODE is the digital input value within the range of 0x000 to 0xFFF. A power-on reset initially resets the internal latches to a defined state (all bits zero).

#### serial interface

Explanation of data transfer: First, the device has to be enabled with  $\overline{CS}$  set to low. Then, a falling edge of FS starts shifting the data bit-per-bit (starting with the MSB) to the internal register on the falling edges of SCLK. After 16 bits have been transferred or FS rises, the content of the shift register is moved to the DAC latch which updates the voltage output to the new level.

The serial interface of the TLV5616 can be used in two basic modes:

- Four wire (with chip select)
- Three wire (without chip select)

Using chip select (four wire mode), it is possible to have more than one device connected to the serial port of the data source (DSP or microcontroller). The interface is compatible with the TMS320 family. Figure 15 shows an example with two TLV5616s connected directly to a TMS320 DSP.

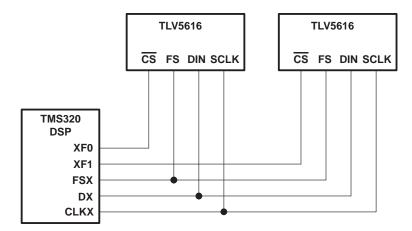


Figure 15. TMS320 Interface

#### **APPLICATION INFORMATION**

#### serial interface (continued)

If there is no need to have more than one device on the serial bus, then  $\overline{CS}$  can be tied low. Figure 16 shows an example of how to connect the TLV5616 to a TMS320, SPI, or Microwire port using only three pins.

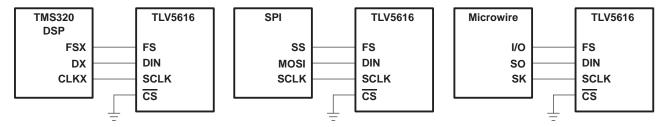


Figure 16. Three-Wire Interface

Notes on SPI and Microwire: Before the controller starts the data transfer, the software has to generate a falling edge on the I/O pin connected to FS. If the word width is 8 bits (SPI and Microwire), two write operations must be performed to program the TLV5616. After the write operation(s), the DAC output is updated automatically on the sixteenth positive clock edge.

# serial clock frequency and update rate

The maximum serial clock frequency is given by:

$$f_{SCLKmax} = \frac{1}{t_{wH(min)} + t_{wL(min)}} = 20 \text{ MHz}$$

The maximum update rate is:

$$f_{UPDATEmax} = \frac{1}{16 \left(t_{WH(min)} + t_{WL(min)}\right)} = 1.25 \text{ MHz}$$

The maximum update rate is a theoretical value for the serial interface, since the settling time of the TLV5616 has to be considered also.

#### data format

The 16-bit data word for the TLV5616 consists of two parts:

Control bits (D15...D12)
 New DAC value (D11...D0)

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Х	SPD	PWR	Х		New DAC value (12 bits)										

X: don't care

SPD: Speed control bit.  $1 \rightarrow \text{fast mode}$   $0 \rightarrow \text{slow mode}$  PWR: Power control bit.  $1 \rightarrow \text{power down}$   $0 \rightarrow \text{normal operation}$ 

In power down mode, all amplifiers within the TLV5616 are disabled.



#### APPLICATION INFORMATION

#### TLV5616 interfaced to TMS320C203 DSP

#### hardware interfacing

Figure 17 shows an example how to connect the TLV5616 to a TMS320C203 DSP. The serial interface of the TLV5616 is ideally suited to this configuration, using a maximum of four wires to make the necessary connections. In applications where only one synchronous serial peripheral is used, the interface can be simplified even further by pulling  $\overline{CS}$  low all the time as shown in the figure.

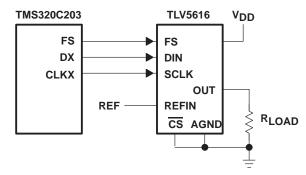


Figure 17. TLV5616 to DSP Interface

#### software

No setup procedure is needed to access the TLV5616. The output voltage can be set using just a single command.

```
out data_addr, SDTR
```

Where data\_addr points to an address location holding the control bits and the 12 data bits providing the output voltage data. SDTR is the address of the transmit FIFO of the synchronous serial port.

The following code shows how to use the timer of the TMS320C203 as a time base to generate a voltage ramp with the TLV5616.

A timer interrupt is generated every 205  $\mu$ s. The corresponding interrupt service routine increments the output code (stored at 0x0064) for the DAC, adds the DAC control bits to the four most significant bits, and writes the new code to the TLV5616. The resulting period of the saw waveform is:

```
\pi = 4096 \times 205 \text{ E-6 s} = 0.84 \text{ s}
```

```
;* Title : Ramp generation with TLV5616
;* Version : 1.0
;* DSP
      : TI TMS320C203
;* © (1998) Texas Instruments Incorporated
;----- I/O and memory mapped regs -----
    .include "regs.asm"
;---- vectors -----
    .ps
          0h
    b
          start
    h
          TNT1
    b
          INT23
    b
          TIM_ISR
```



#### **APPLICATION INFORMATION**

```
; * Main Program
1000h
    .ps
    .entry
start:
; disable interrupts
    setc INTM
splk #0ffffh, IFR
                   ; disable maskable interrupts
           #0004h, IMR
    splk
; set up the timer to interrupt ever 205uS
          #0000h, 60h
    splk
           #00FFh, 61h
    splk
    out
           61h, PRD
           60h, TIM
    out
           #0c2fh, 62h
    splk
           62h, TCR
    out
; Configure SSP to use internal clock, internal frame sync and burst mode
    splk
           #0CC0Eh, 63h
           63h, SSPCR
    out
           #0CC3Eh, 63h
    splk
           63h, SSPCR
    out
           #0000h, 64h; set initial DAC value
    splk
; enable interrupts
    clrc
           INTM
                   ; enable maskable interrupts
; loop forever!
     idle
                    ; wait for interrupt
next:
       b
           next
; all else fails stop here
done: b done
                    ; hang there
;* Interrupt Service Routines
INT1:
      ret
                    ;do nothing and return
                    ;do nothing and return
INT23:
       ret
TIM_ISR:
       lacl
           64h
                    ; restore counter value to ACC
           #1h
                    ; increment DAC value
       add
           #0FFFh
                    ; mask 4 MSBs
       and
       sacl 64h
                    ; store 12 bit counter value
           #4000h
                    ; set DAC control bits
       or
       sacl 65h
                    ; store DAC value
       out 65h, SDTR ; send data
       clrc intm
                   ; re-enable interrupts
       ret
.END
```



#### APPLICATION INFORMATION

# TLV5616 interfaced to MCS51® microcontroller

# hardware interfacing

Figure 18 shows an example of how to connect the TLV5616 to an MCS51<sup>®</sup> compatible microcontroller. The serial DAC input data and external control signals are sent via I/O port 3 of the controller. The serial data is sent on the RxD line, with the serial clock output on the TxD line. P3.4 and P3.5 are configured as outputs to provide the chip select and frame sync signals for the TLV5616.

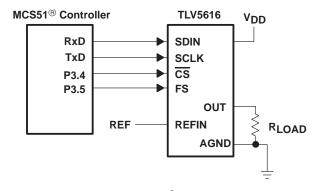


Figure 18. TLV5616 to MCS51® Controller Interface

#### software

The example program puts out a sine wave on the OUT pin.

The on-chip timer is used to generate interrupts at a fixed frequency. The related interrupt service routine fetches and writes the next sample to the DAC. The samples are stored in a lookup table, which describes one full period of a sine wave.

The serial port of the controller is used in mode 0, which transmits 8 bits of data on RxD, accompanied by a synchronous clock on TxD. Two writes concatenated together are required to write a complete word to the TLV5616. The CS and FS signals are provided in the required fashion through control of I/O port 3, which has bit addressable outputs.

```
;* Title : Ramp generation with TLV5616
;* Version : 1.0
        : INTEL MCS51®
; * MCII
;* © (1998) Texas Instruments Incorporated
; Program function declaration
NAME
     GENSINE
MAIN
     SEGMENT
                CODE
                CODE
ISR
     SEGMENT
SINTBL SEGMENT
                CODE
     SEGMENT
                DATA
VAR1
STACK SEGMENT
                IDATA
; Code start at address 0, jump to start
  CSEG AT 0
```

MCS is a registered trademark of Intel Corporation



# TLV5616C, TLV5616I 2.7 V TO 5.5 V LOW POWER 12-BIT DIGITAL-TO-ANALOG CONVERTERS WITH POWER DOWN

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#### **APPLICATION INFORMATION**

```
; Execution starts at address 0 on power-up.
   LJMP
            start
; Code in the timerO interrupt vector
   CSEG AT OBH
          timer0isr; Jump vector for timer 0 interrupt is 000Bh
;------
; Define program variables
   RSEG
rolling_ptr: DS 1
; Interrupt service routine for timer 0 interrupts
   RSEG
            ISR
timer0isr:
   PUSH
          PSW
   PUSH
           ACC
                           ; set CSB low
   CLR
                           ; set FS low
   CLR
   ; The signal to be output on the dac is a sine function. One cycle of a sine wave is
   ; held in a table @ sinevals as 32 samples of msb, lsb pairs (64 bytes). The pointer,
   ; rolling_ptr, rolls round the table of samples incrementing by 2 bytes (1 sample) on
   ; each interrupt (at the end of this routine).
            DPTR, #sinevals ; set DPTR to the start of the table of sine signal values
   MOV
            A,rolling_ptr ; ACC loaded with the pointer into the sine table
                         ; get msb from the table
   MOVC
            A,@A+DPTR
   ORL
            A, #00H
                           ; set control bits
   MOV
            SBUF,A
                          ; send out msb of data word
   MOVA, rolling_ptr; move rolling pointer in to ACC
                         ; increment ACC holding the rolling pointer
   INC
   MOVC
            A,@A+DPTR
                          ; which is the lsb of this sample, now in ACC
MSB_TX:
   JNB
            TI, MSB_TX ; wait for transmit to complete
                           ; clear for new transmit
   CLR
            TΙ
   MOV
            SBUF,A
                          ; and send out the 1sb
LSB_TX:
            TI, LSB_TX
                       ; wait for lsb transmit to complete
   SETB
            T1
                           ; set FS = 1
   CLR
            ΤI
                           ; clear for new transmit
   MOV
                          ; load ACC with rolling pointer
         A,rolling_ptr
                          ; increment the ACC twice, to get next sample
   INC
   TNC
         Α
         A,#03FH
   ANL
                          ; wrap back round to 0 if >64
         rolling_ptr,A
                         ; move value held in ACC back to the rolling pointer
   MOV
   SETB
                           ; CSB high
   POP
         ACC
   POP
   RETT
; Set up stack
```



#### APPLICATION INFORMATION

```
RSEG STACK
   DS
          10h
                             ; 16 Byte Stack!
; Main Program
   RSEG MAIN
start:
          SP, #STACK-1 ; first set Stack Pointer
   MOV
   CLR
   MOV
        SCON,A
                      ; set serial port 0 to mode 0
                     ; set timer 0 to mode 2 - auto-reload
; set THO for 16.67 kHs interrupts
          TMOD, #02H
   MOV
          TH0,#0C8H
   MOV
   SETB
                       ; set FS = 1
         T1
   SETB TO
                       ; set CSB = 1
   SETB ET0
                      ; enable timer 0 interrupts
   SETB EA
                      ; enable all interrupts
         rolling_ptr,A
   MOV
                             ; set rolling pointer to 0
   SETB TRO
                             ; start timer 0
always:
   SJMP
         always
                             ; while(1) !
   RET
; Table of 32 sine wave samples used as DAC data
   RSEG SINTBL
sinevals:
   DM
          01000H
   DW
          0903EH
   DW
         05097H
   DW
         0305CH
   DW
         0B086H
   DM
          070CAH
   DW
          OFOEOH
          0F06EH
   DW
   DW
          0F039H
          OF06EH
   DW
         OFOEOH
   DW
   DW
         070CAH
   DW
         0B086H
   DW
         0305CH
   DW
          05097H
   DW
          0903EH
   DW
          01000H
   DW
          06021H
   DW
          OAOE8H
   DW
          0C063H
   DW
         040F9H
          080B5H
   DW
          0009FH
   DW
          00051H
   DW
          00026H
   DW
          00051H
   DW
          0009FH
          080B5H
   DW
   DM
          040F9H
   DW
         0C063H
   DW
          0A0E8H
   DW
          06021H
END
```

#### **APPLICATION INFORMATION**

# linearity, offset, and gain error using single ended supplies

When an amplifier is operated from a single supply, the voltage offset can still be either positive or negative. With a positive offset, the output voltage changes on the first code change. With a negative offset, the output voltage may not change with the first code, depending on the magnitude of the offset voltage.

The output amplifier attempts to drive the output to a negative voltage. However, because the most negative supply rail is ground, the output cannot drive below ground and clamps the output at 0 V.

The output voltage then remains at zero until the input code value produces a sufficient positive output voltage to overcome the negative offset voltage, resulting in the transfer function shown in Figure 19.

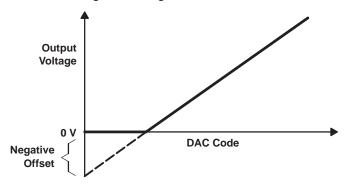


Figure 19. Effect of Negative Offset (Single Supply)

This offset error, not the linearity error, produces this breakpoint. The transfer function would have followed the dotted line if the output buffer could drive below the ground rail.

For a DAC, linearity is measured between zero-input code (all inputs 0) and full-scale code (all inputs 1) after offset and full scale are adjusted out or accounted for in some way. However, single supply operation does not allow for adjustment when the offset is negative due to the breakpoint in the transfer function. So the linearity is measured between full-scale code and the lowest code that produces a positive output voltage.

#### power-supply bypassing and ground management

Printed circuit boards that use separate analog and digital ground planes offer the best system performance. Wire-wrap boards do not perform well and should not be used. The two ground planes should be connected together at the low-impedance power-supply source. The best ground connection may be achieved by connecting the DAC AGND terminal to the system analog ground plane making sure that analog ground currents are well managed and there are negligible voltage drops across the ground plane.

A 0.1- $\mu F$  ceramic-capacitor bypass should be connected between  $V_{DD}$  and AGND and mounted with short leads as close as possible to the device. Use of ferrite beads may further isolate the system analog supply from the digital power supply.

Figure 20 shows the ground plane layout and bypassing technique.

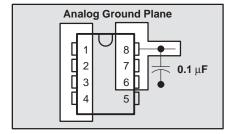


Figure 20. Power-Supply Bypassing



#### APPLICATION INFORMATION

#### definitions of specifications and terminology

# integral nonlinearity (INL)

The relative accuracy or integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale excluding the effects of zero code and full-scale errors.

#### differential nonlinearity (DNL)

The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.

#### zero-scale error (E<sub>7S</sub>)

Zero-scale error is defined as the deviation of the output from 0 V at a digital input value of 0.

#### gain error (E<sub>G</sub>)

Gain error is the error in slope of the DAC transfer function.

# signal-to-noise ratio + distortion (S/N+D)

S/N+D is the ratio of the rms value of the output signal to the rms sum of all other spectral components below the Nyquist frequency, including harmonics but excluding dc. The value for S/N+D is expressed in decibels.

#### spurious free dynamic range (SFDR)

SFDR is the difference between the rms value of the output signal and the rms value of the largest spurious signal within a specified bandwidth. The value for SFDR is expressed in decibels.

#### total harmonic distortion (THD)

THD is the ratio of the rms sum of the first six harmonic components to the rms value of the fundamental signal and is expressed in decibels.

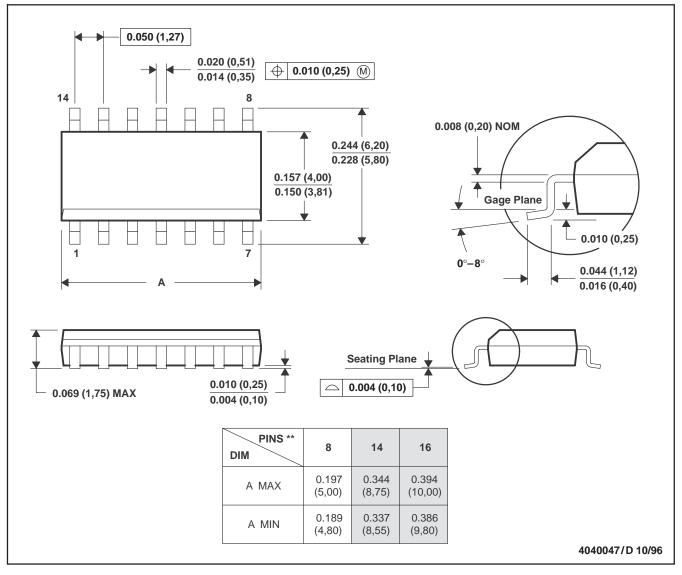


#### **MECHANICAL DATA**

# D (R-PDSO-G\*\*)

#### 14 PIN SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012



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